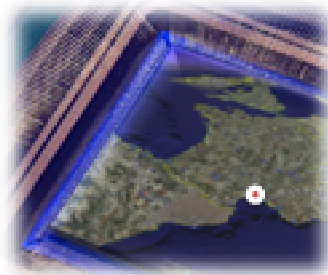# IEEE Third Symposium on Industrial Embedded Systems
SIES'2008
June 11 - 13, 2008 – Montpellier La Grande Motte, FRANCE

Call For Papers

Background : Application domains have had a considerable impact on the evolution of embedded systems, in terms of required methodologies and supporting tools and resulting technologies. SoCs and SoPC are slowly making inroads into the area of industrial automation to implement complex field-area intelligent devices which integrate the intelligent sensor/actuator functionality by providing on-chip signal conversion, data processing, and communication functions. There is a growing tendency to network field-area intelligent devices around industrial type of communication networks. Similar trends appear in the automotive electronic systems where the Electronic Control Units, typically implemented as heterogeneous system-on-chip, are networked by means of one safety-critical communication protocol. The design of this kind of networked embedded systems (this includes also hard real-time industrial control systems) is a challenge in itself due to the distributed nature of processing elements, sharing common communication medium, and safety-critical requirements, to mention some.

Aim : The aim of the symposium is to bring together researchers and practitioners from industry and academia and provide them with a platform to report on recent developments, deployments, technology trends and research results, as well as initiatives related to embedded systems and their applications in a variety of industrial environments.

Special Sessions: To enhance the technical program and focus on specific topics and areas, the SIES'2008 Symposium will include special sessions, in addition to regular ones. Special sessions can cover subjects or cross-subjects belonging to the topics of interest, or novel topics related with the ones identified within the topics of interest.

Topics within the scope of the symposium include:

- Embedded Systems
- System-on-Chip and Network-on-Chip Design & Testing
- Networked Embedded Systems
- Embedded Applications / Automotive / Avionics systems
- Multi-Processors Systems-on-Chips
- Sensors networks and ubiquitous computing
- Application of Reconfigurable and Adaptive Systems
- Fault-tolerant embedded systems and applications

Author's Schedule:

Extended Deadline for submission of long papers:	**February 18, 2008**
Notification of acceptance for long papers:	April 1, 2008
Deadline for submission of final manuscripts for long papers:	April 22, 2008
Extended Deadline for submission of WIP* and IP** papers:	**March 28, 2008**
Notification of acceptance of WIP and IP papers:	April 25, 2008
Deadline for submission of final manuscripts of WIP & IP papers:	May 2, 2008

* WIP: Work in Progress   ** IP: Industry Practice

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